

Title (en)

METAL-CONTACTED SUBSTRATE AND METHOD FOR THE PRODUCTION THEREOF

Title (de)

METALLISCH KONTAKTIERTES SUBSTRAT SOWIE VERFAHREN ZU DESSEN HERSTELLUNG

Title (fr)

SUBSTRAT À CONTACT MÉTALLIQUE ET PROCÉDÉ DE FABRICATION DE CELUI-CI

Publication

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Application

EP 10787284 A 20101123

Priority

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Abstract (en)

[origin: WO2011063933A1] The invention relates to a metal-contacted substrate (1), in which at least one surface of the substrate is entirely or partially provided with a metal contact (2, 3). For mechanical stabilisation, the metal contact is provided with a matrix material (5). The invention also relates to a method for producing such a substrate.

IPC 8 full level

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Citation (search report)

See references of WO 2011063933A1

Citation (examination)

- DE 19752413 A1 19981203 - MITSUBISHI ELECTRIC CORP [JP]
- WO 9222928 A1 19921223 - MOBIL SOLAR ENERGY CORP [US]
- US 2007256733 A1 20071108 - KARAKIDA SHOICHI [JP], et al

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